Drill Table

FOR 7.62MM DRILL +/-.007MM
FOR 12MM DRILL +/-.12MM
FOR 18MM DRILL +/-.18MM
FOR WPN DRILL +/-2.5MM

Layer Name | Material | Thickness | Constant | Board Layer Stack
---|---|---|---|---
1 | Top Overlay | | | |
2 | Top Solder | Solder Resist (Ni, 4.5um) | 3.5 | |
3 | Top Layer | Copper (L=40um) | | |
4 | Character(1) | TD+/- High Tg 180.20um(4.83) | 4.8 | |
5 | Bottom Layer | Copper (L=40um) | | |
6 | Bottom Solder | Solder Resist (Ni, 4.5um) | 3.5 | |
7 | Bottom Overlay | | | |

DESIGN INFORMATION

BOARD SIZE: (Refer also Arrray Panel Profiling Information) 110MM x 85MM
Number of Layers: 2
VIA TRACK WIDTH: 1.00MM
VIA CLEARANCE: 0.30MM
VIA VIA DLL SIZE: 2.25MM
HOLES: ANULAR RING 5.50MM EXTERNAL
PER FRI-9802: CLASS 2 LEVEL C
REGISTRATION TOLERANCES METAL +/- 0.50MM HOLES +/- 0.30MM

MATERIAL:
| FR-4 - 163C +/-.10% | OTHER |
| FR-4 High Tg | OTHER |
| AS SHOWN | OTHER |
| X MARKS FIEL | OTHER |

BEND & THICKNESS:

COX THICKNESS: 0.20MM
OUTER | 1.4MM (top) | 2.0MM (bottom) | 1.4MM (top) | OTHER |
INNER | 1.4MM (top) | 2.0MM (2X2) | OTHER |

REFERENCE PLATE IN COPPER THICKNESS: X MARKS FIEL

BOND FINISH:
SUBSCREEN COLOR: X MARKS FIEL
SOLDER RESIST COLOR: X MARKS FIEL

SURFACE FINISH:
| ANODISED GOLD (800) | EXCEPT |
| AS SHOWN | OTHER |

ARRAY/PANEL:
OUT AND TRIM PER MECH LAYER 1
NC ROUTE: X V SCORE

CERTIFICATION:
MATERIALS CRITERIA FOR ALL LAYERS TO MEET OR EXCEED THE REQUIREMENTS OF:
| ANG PC-4-002 TYPE 3 CLASS 2 |
| ANG PC-4-002 TYPE 3 CLASS 2 |

ADDITIONAL REQUIREMENTS: VIA TESTING YES |
MICROSECTION: YES | IN LAMINATE CONTROL | OTHER |

SAME BOARD ELECT TESTS: X MARKS FIEL | OTHER |
MANUFACTURERS: X MARKS FIEL | OTHER |

SINIA DEC Has Not In VectorControl

PUBLIC RELEASE

PROJECT FILE: T1301-0041
DESIGNED FOR:
Public Release
REV/REV 1

T1301-0041-CL.00041

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<table>
<thead>
<tr>
<th>Layer</th>
<th>Name</th>
<th>Material</th>
<th>Thickness</th>
<th>Constant</th>
<th>Board Layer Status</th>
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<tbody>
<tr>
<td>1</td>
<td>Top Overlay</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>Top Solder</td>
<td>Solder Resin</td>
<td>0.4mm</td>
<td>3.5</td>
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<tr>
<td>3</td>
<td>Top Layer</td>
<td>Copper</td>
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<td>4.8</td>
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<tr>
<td>4</td>
<td>Intermetal</td>
<td>FR-4 High TG</td>
<td>1.4mm</td>
<td>4.8</td>
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<td>5</td>
<td>Bottom Layer</td>
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<td>3.5</td>
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<tr>
<td>6</td>
<td>Bottom Solder</td>
<td>Solder Resin</td>
<td>0.4mm</td>
<td>3.5</td>
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</tr>
<tr>
<td>7</td>
<td>Bottom Overlay</td>
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